

Docket No.: P16666

*Utility Patent Application*

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Patent Application of:	)	
	)	
<b>Shriram Ramanathan et al.</b>	)	
	)	Confirmation No.: 1525
Serial No.: 10/611,395	)	
	)	Examiner: Heather Anne Doty
Filed: June 30, 2003	)	
	)	Art Unit: 2813
For: <b>METHODS FOR BONDING WAFERS USING A</b>	)	
<b>METAL INTERLAYER</b>	)	
_____	)	

**RESPONSE TO OFFICE ACTION**

Mail Stop: Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## **INTRODUCTORY COMMENTS**

Sir:

This paper is being filed in response to an Office Action having a mailing date of April 17, 2007 that Applicant has received from the Patent Office and that relates to the above-identified patent application. Applicant respectfully requests that the patent application be reconsidered in view of the amendments and remarks presented hereinafter, which are submitted as a full and complete response to the aforementioned Office Action.

This paper is timely filed upon the mailing of same with an executed certificate of mailing on or before July 17, 2007. No fees are believed to be due by virtue of the filing of this paper. However, if it is determined that any fees are in fact due, please charge such fees to Deposit Account No. 50-0221.

Claims 1-5, 7-20, and 22-27 remain in the subject patent application. Claims 1, 12, 13, and 27 are amended and claims 6 and 21 are canceled herein. Claims 28-42 were canceled in an earlier paper. No claims are added herein.